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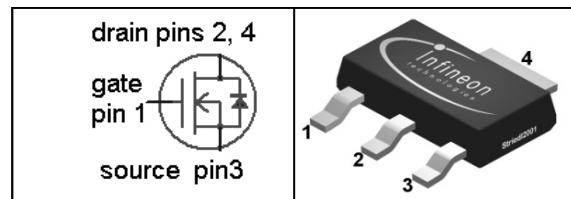


**SIPMOS<sup>®</sup> Small-Signal-Transistor**
**Features**

- N-channel
- Depletion mode
- $dv/dt$  rated
- Available with  $V_{GS(th)}$  indicator on reel
- Pb-free lead plating; RoHS compliant
- Qualified according to AEC Q101
- Halogen-free according to IEC61249-2-21


**Product Summary**

$V_{DS}$	200	V
$R_{DS(on),max}$	3.5	$\Omega$
$I_{DSS,min}$	0.14	A

**PG-SOT223**


Type	Package	Tape and Reel Information	Marking	Packaging
BSP149	PG-SOT223	H6327: 1000 pcs/reel	BSP149	Non dry
BSP149	PG-SOT223	H6906: 1000 pcs/reel sorted in $V_{GS(th)}$ bands1)	BSP149	Non dry

**Maximum ratings, at  $T_j=25\text{ }^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	$I_D$	$T_A=25\text{ }^\circ\text{C}$	0.66	A
		$T_A=70\text{ }^\circ\text{C}$	0.53	
Pulsed drain current	$I_{D,pulse}$	$T_A=25\text{ }^\circ\text{C}$	2.6	
Reverse diode $dv/dt$	$dv/dt$	$I_D=0.66\text{ A}$ , $V_{DS}=160\text{ V}$ , $di/dt=200\text{ A}/\mu\text{s}$ , $T_{j,max}=150\text{ }^\circ\text{C}$	6	kV/ $\mu\text{s}$
Gate source voltage	$V_{GS}$		$\pm 20$	V
ESD Class (JESD22-A114-HBM)			1B (>500, <600)	
Power dissipation	$P_{tot}$	$T_A=25\text{ }^\circ\text{C}$	1.8	W
Operating and storage temperature	$T_j, T_{stg}$		-55 ... 150	$^\circ\text{C}$
IEC climatic category; DIN IEC 68-1			55/150/56	

<sup>1)</sup> see table on next page and diagram 11

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
<b>Thermal characteristics</b>						
Thermal resistance, junction - soldering point (pin 4)	$R_{thJS}$		-	-	25	K/W
SMD version, device on PCB	$R_{thJA}$	minimal footprint	-	-	115	
		6 cm <sup>2</sup> cooling area <sup>1)</sup>	-	-	70	

**Electrical characteristics, at  $T_j=25\text{ °C}$ , unless otherwise specified**

**Static characteristics**

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=-3\text{ V}, I_D=250\text{ }\mu\text{A}$	200	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=3\text{ V}, I_D=400\text{ }\mu\text{A}$	-2.1	-1.4	-1	
Drain-source cutoff current	$I_{D(off)}$	$V_{DS}=200\text{ V}, V_{GS}=-3\text{ V}, T_j=25\text{ °C}$	-	-	0.1	$\mu\text{A}$
		$V_{DS}=200\text{ V}, V_{GS}=-3\text{ V}, T_j=125\text{ °C}$	-	-	5	
Gate-source leakage current	$I_{GSS}$	$V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$	-	-	10	nA
On-state drain current	$I_{DSS}$	$V_{GS}=0\text{ V}, V_{DS}=10\text{ V}$	140	-	-	mA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=0\text{ V}, I_D=70\text{ mA}$	-	1.7	3.5	$\Omega$
		$V_{GS}=10\text{ V}, I_D=660\text{ mA}$	-	1.0	1.8	
Transconductance	$g_{fs}$	$ V_{DS} >2 I_D R_{DS(on)max}, I_D=0.48\text{ A}$	0.4	0.8	-	S

**Threshold voltage  $V_{GS(th)}$  sorted in bands<sup>3)</sup>**

J	$V_{GS(th)}$	$V_{DS}=3\text{ V}, I_D=400\text{ }\mu\text{A}$	-1.2	-	-1	V
K			-1.35	-	-1.15	
L			-1.5	-	-1.3	
M			-1.65	-	-1.45	
N			-1.8	-	-1.6	

<sup>2)</sup> Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm<sup>2</sup> (single layer, 70  $\mu\text{m}$  thick) copper area for drain connection. PCB is vertical in still air.

<sup>3)</sup> Each reel contains transistors out of one band whose identifying letter is printed on the reel label. A specific band cannot be ordered separately.

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

**Dynamic characteristics**

Input capacitance	$C_{iss}$	$V_{GS}=-3\text{ V}, V_{DS}=25\text{ V},$ $f=1\text{ MHz}$	-	326	430	pF
Output capacitance	$C_{oss}$		-	41	55	
Reverse transfer capacitance	$C_{rss}$		-	17	25	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=100\text{ V},$ $V_{GS}=-2\dots 7\text{ V},$ $I_D=0.50\text{ A}, R_G=6\ \Omega$	-	5.1	7.7	ns
Rise time	$t_r$		-	3.4	5.1	
Turn-off delay time	$t_{d(off)}$		-	45	68	
Fall time	$t_f$		-	21	31	

**Gate Charge Characteristics**

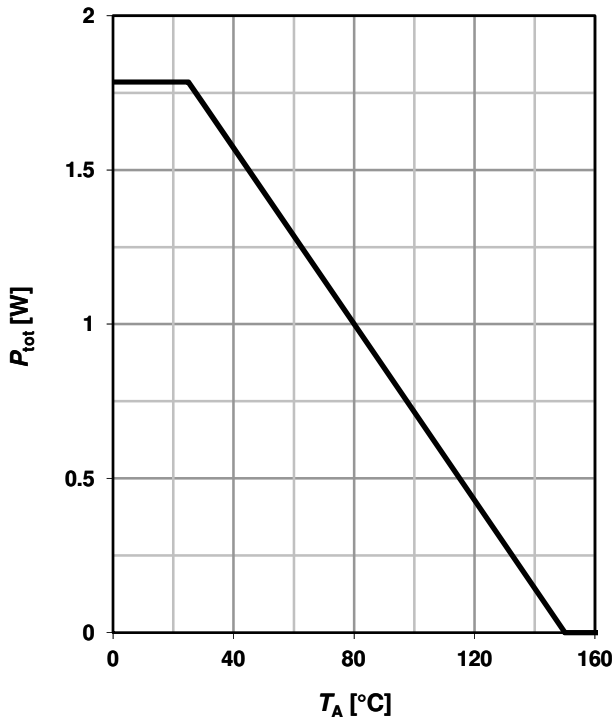
Gate to source charge	$Q_{gs}$	$V_{DD}=160\text{ V},$ $I_D=0.05\text{ A},$ $V_{GS}=-3\text{ to }5\text{ V}$	-	0.74	1.0	nC
Gate to drain charge	$Q_{gd}$		-	5.6	8.4	
Gate charge total	$Q_g$		-	11	14	
Gate plateau voltage	$V_{plateau}$		-	0.16	-	V

**Reverse Diode**

Diode continuous forward current	$I_S$	$T_A=25\text{ }^\circ\text{C}$	-	-	0.66	A
Diode pulse current	$I_{S,pulse}$		-	-	2.6	
Diode forward voltage	$V_{SD}$	$V_{GS}=-3\text{ V}, I_F=0.66\text{ A},$ $T_J=25\text{ }^\circ\text{C}$	-	0.9	1.2	V
Reverse recovery time	$t_{rr}$	$V_R=100\text{ V}, I_F=0.5\text{ A},$ $di_F/dt=100\text{ A}/\mu\text{s}$	-	42	65	ns
Reverse recovery charge	$Q_{rr}$		-	60	90	nC

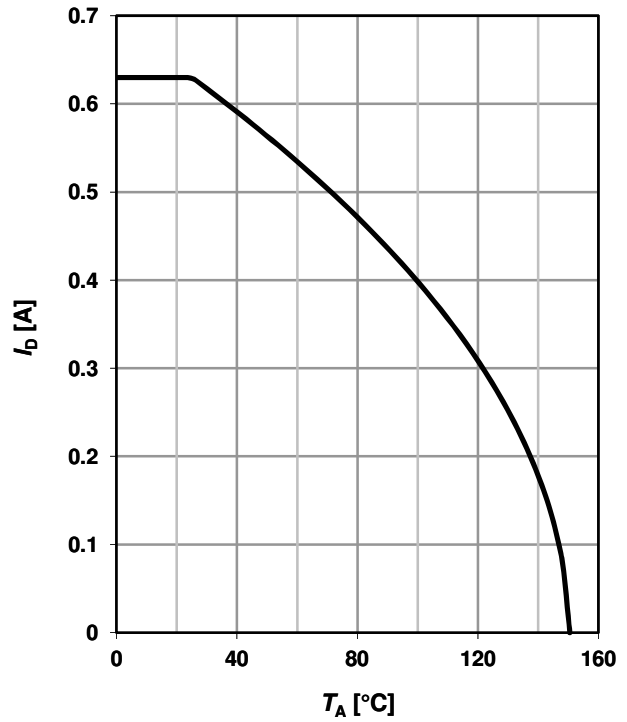
### 1 Power dissipation

$$P_{tot}=f(T_A)$$



### 2 Drain current

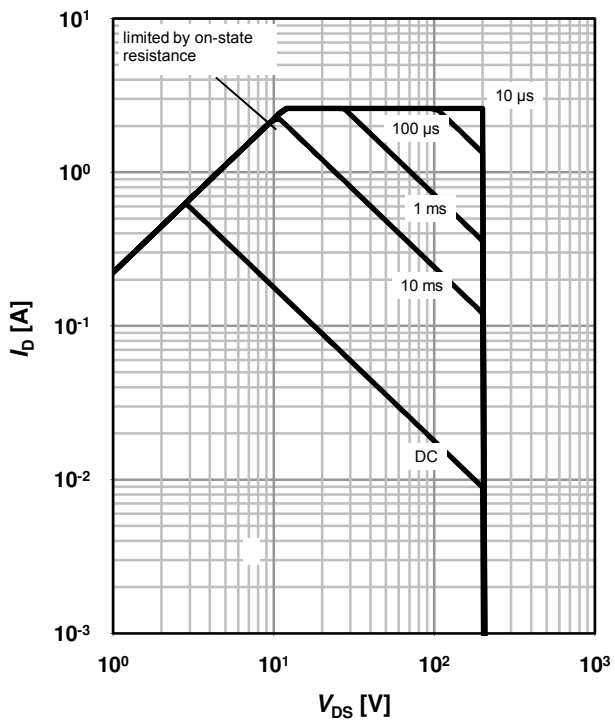
$$I_D=f(T_A); V_{GS} \geq 10 \text{ V}$$



### 3 Safe operating area

$$I_D=f(V_{DS}); T_A=25 \text{ °C}; D=0$$

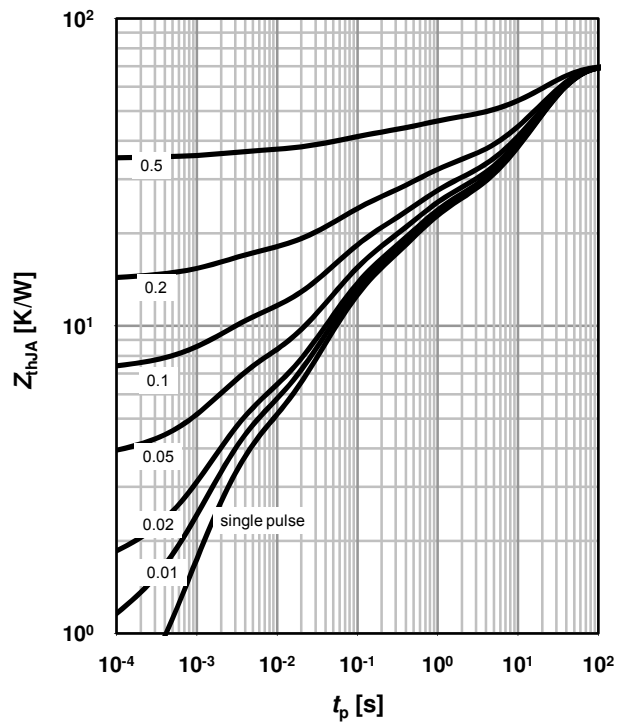
parameter:  $t_p$



### 4 Max. transient thermal impedance

$$Z_{thJA}=f(t_p)$$

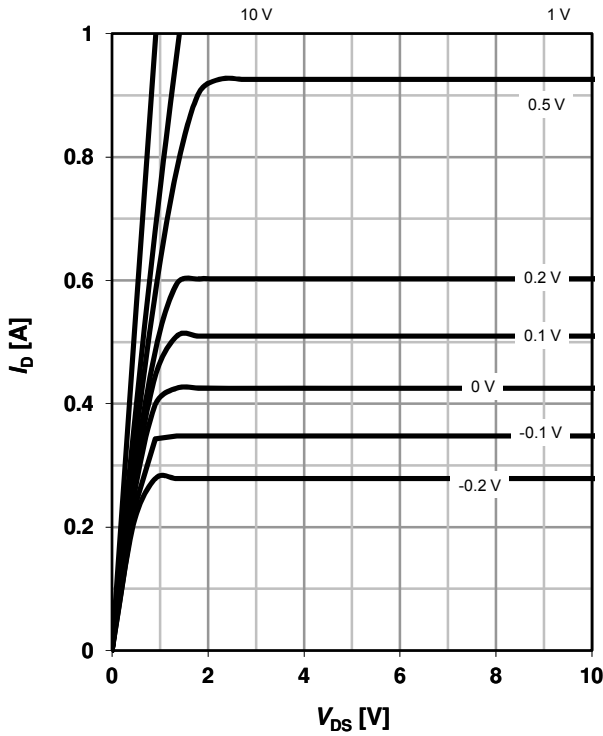
parameter:  $D=t_p/T$



**5 Typ. output characteristics**

$I_D = f(V_{DS}); T_j = 25\text{ }^\circ\text{C}$

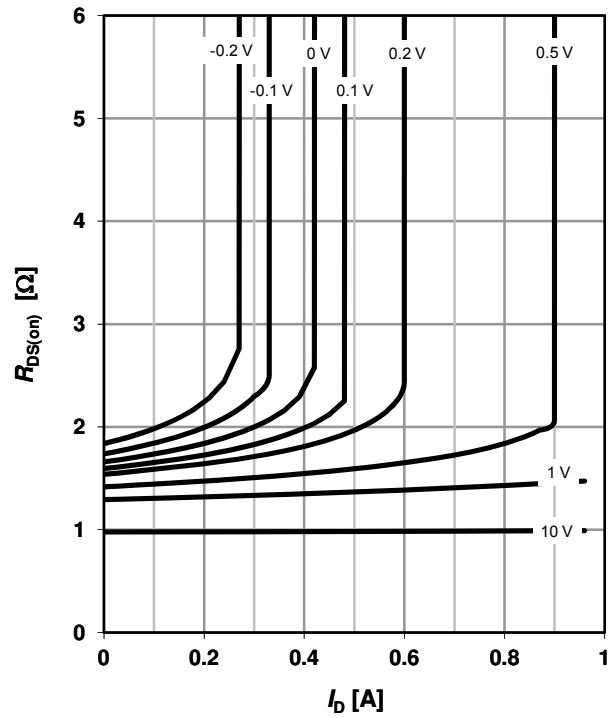
parameter:  $V_{GS}$



**6 Typ. drain-source on resistance**

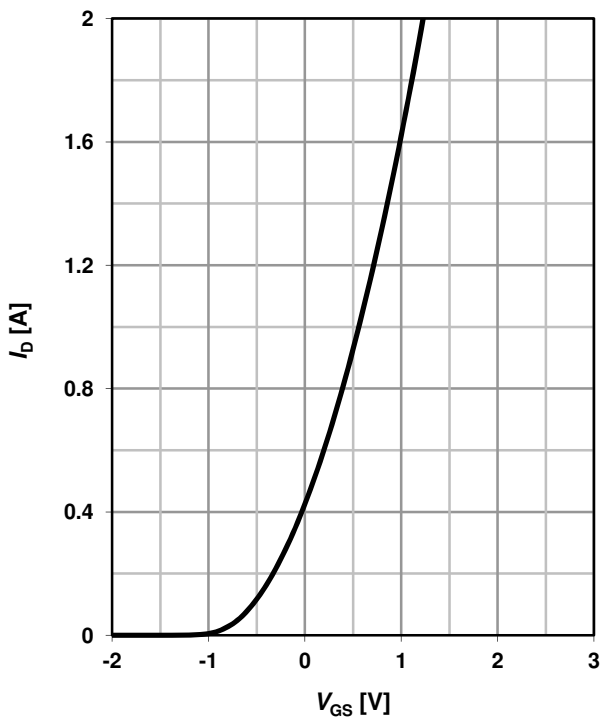
$R_{DS(on)} = f(I_D); T_j = 25\text{ }^\circ\text{C}$

parameter:  $V_{GS}$



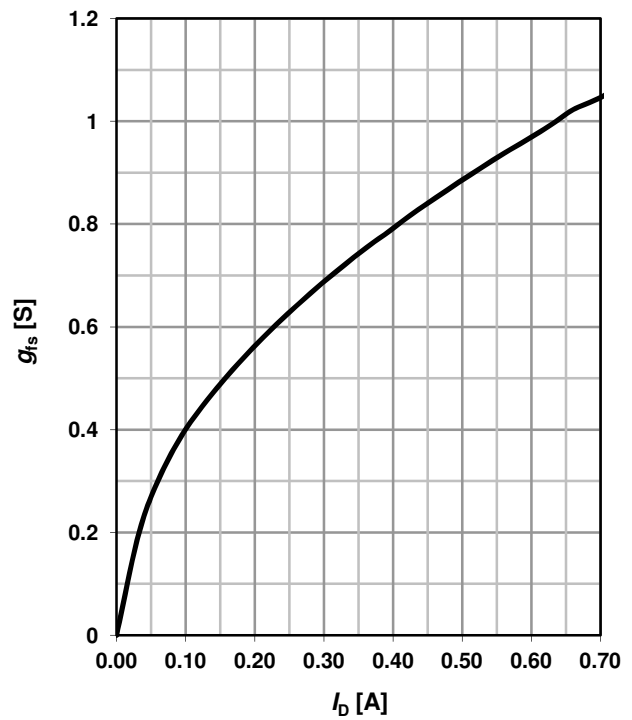
**7 Typ. transfer characteristics**

$I_D = f(V_{GS}); |V_{DS}| > 2|I_D|R_{DS(on)max}$



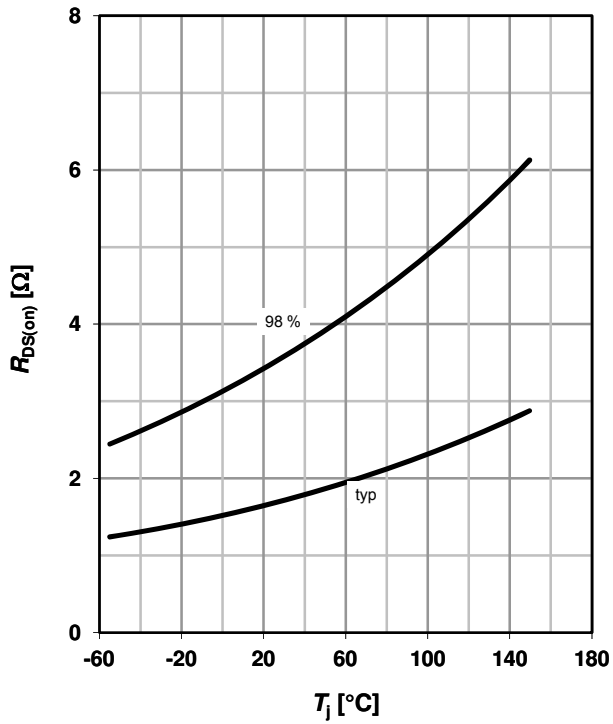
**8 Typ. forward transconductance**

$g_{fs} = f(I_D); T_j = 25\text{ }^\circ\text{C}$



**9 Drain-source on-state resistance**

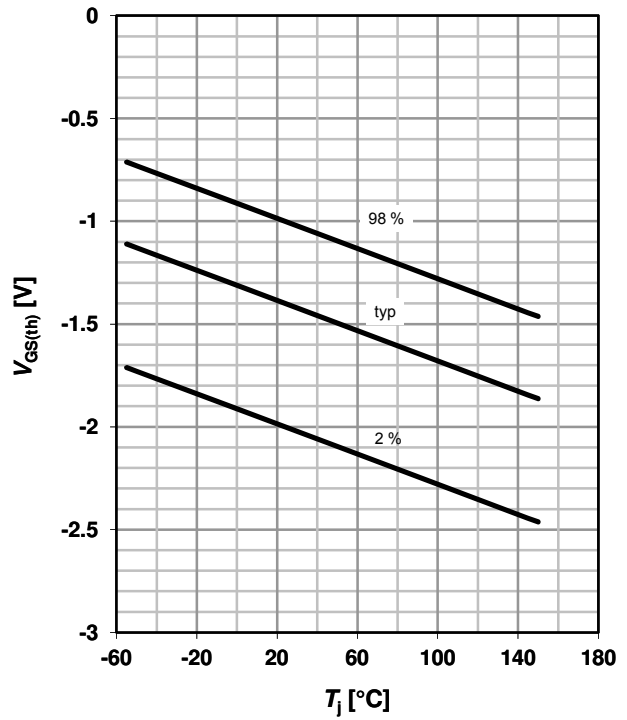
$R_{DS(on)}=f(T_j); I_D=0.07\text{ A}; V_{GS}=0\text{ V}$



**10 Typ. gate threshold voltage**

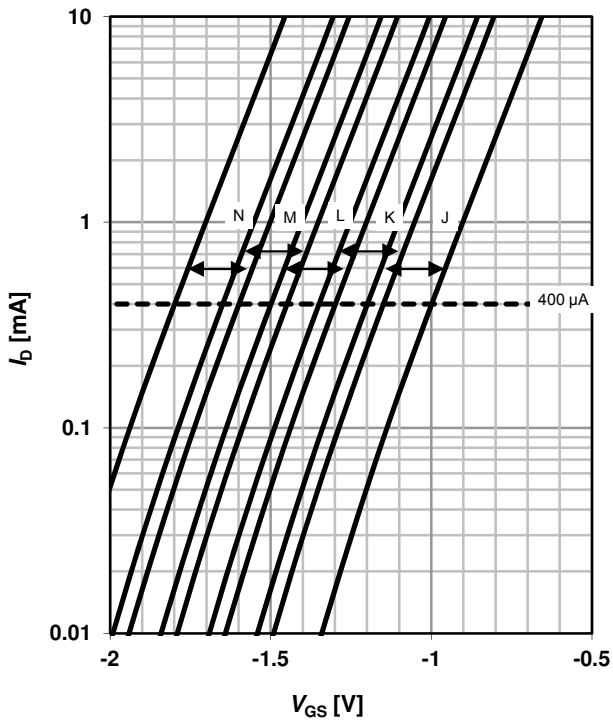
$V_{GS(th)}=f(T_j); V_{DS}=3\text{ V}; I_D=400\text{ }\mu\text{A}$

parameter:  $I_D$



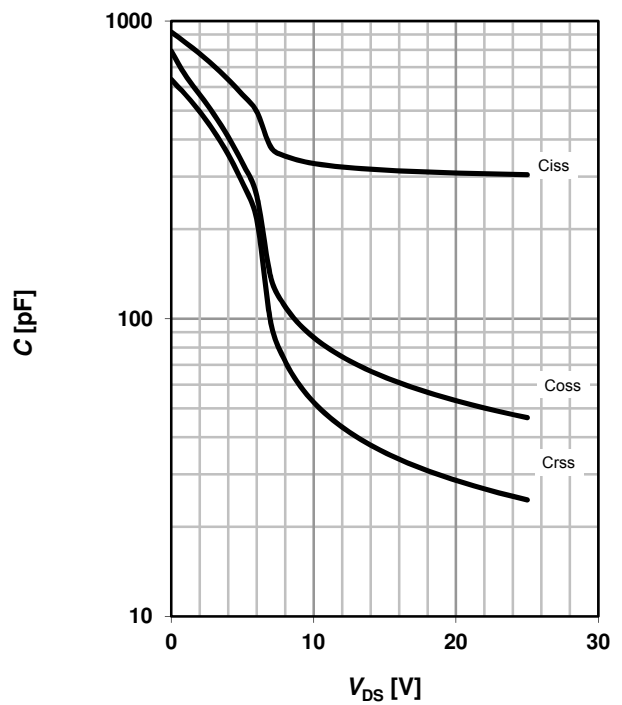
**11 Threshold voltage bands**

$I_D=f(V_{GS}); V_{DS}=3\text{ V}; T_j=25\text{ }^\circ\text{C}$



**12 Typ. capacitances**

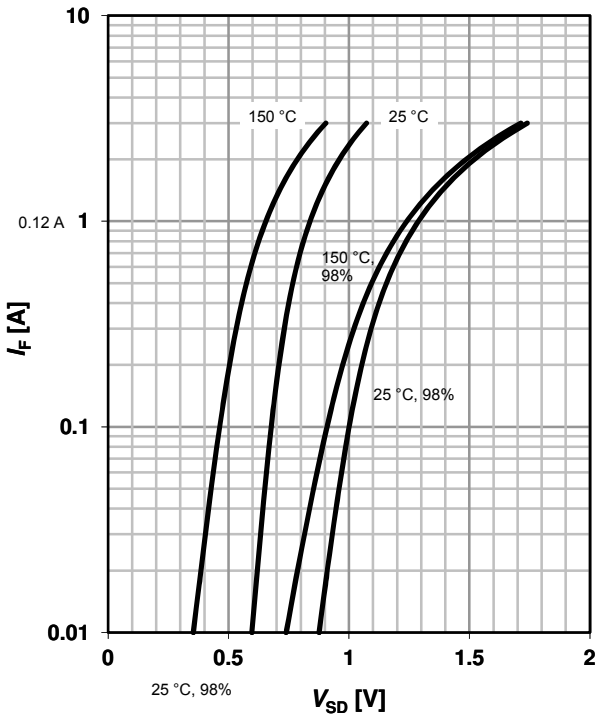
$C=f(V_{DS}); V_{GS}=-3\text{ V}; f=1\text{ MHz}$



**13 Forward characteristics of reverse diode**

$I_F=f(V_{SD})$

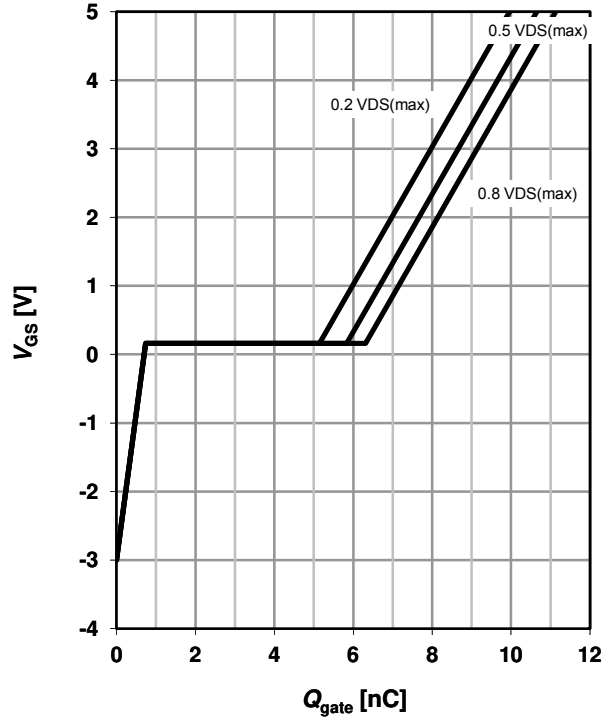
parameter:  $T_j$



**15 Typ. gate charge**

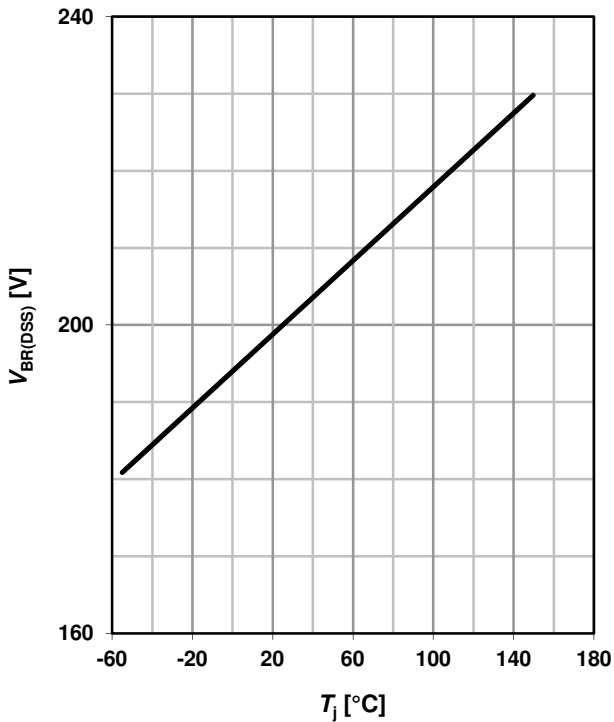
$V_{GS}=f(Q_{gate}); I_D=0.5\text{ A pulsed}$

parameter:  $V_{DD}$



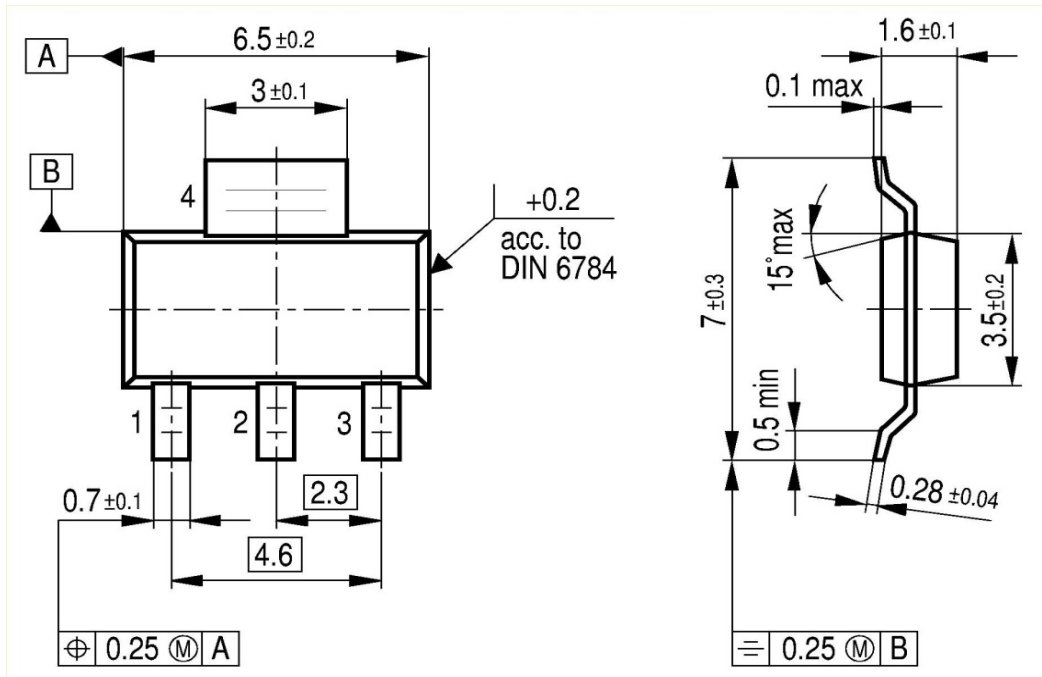
**16 Drain-source breakdown voltage**

$V_{BR(DSS)}=f(T_j); I_D=250\ \mu\text{A}$

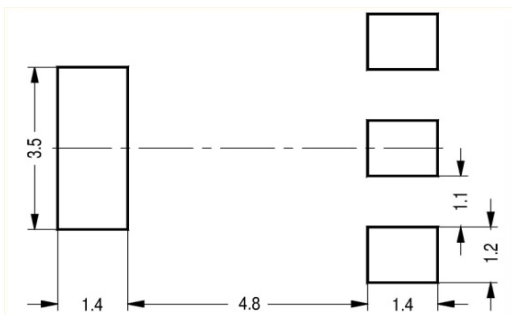




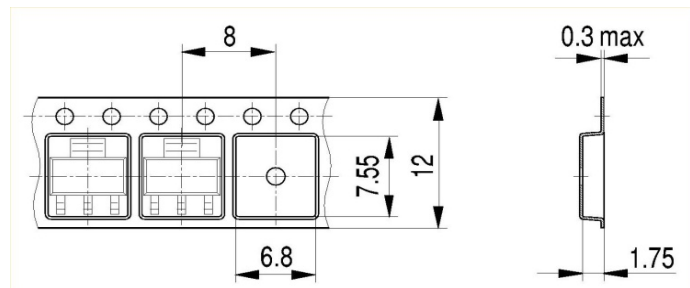
Package Outline:



Footprint:



Packaging:



Dimensions in mm

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